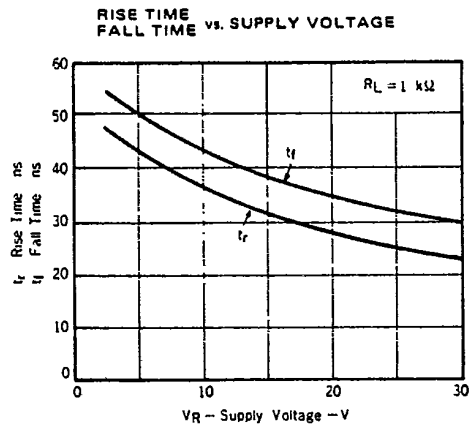
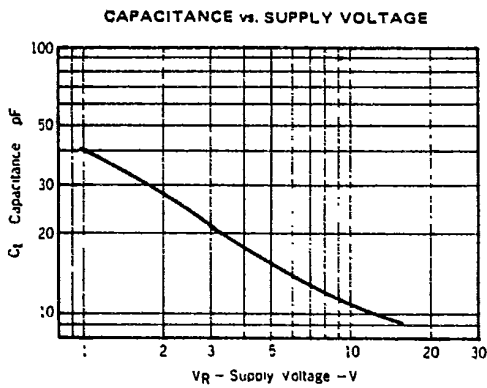
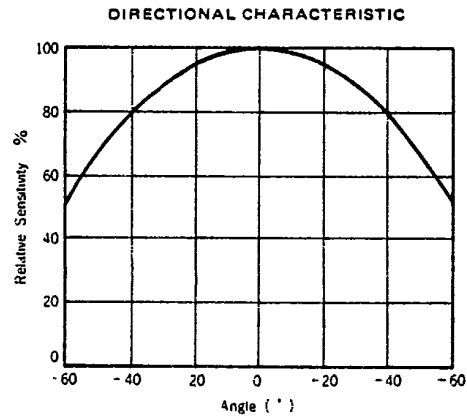
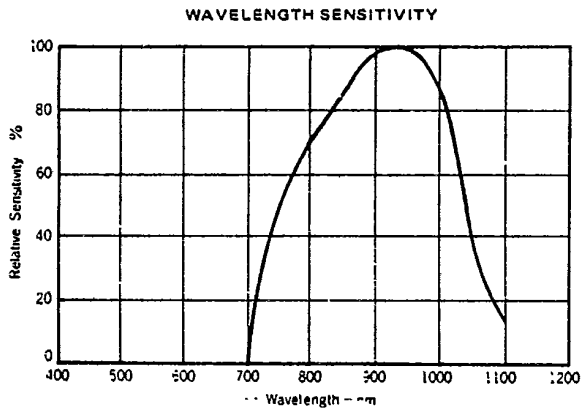


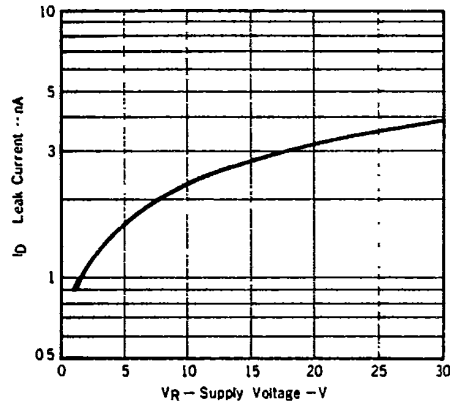
ELECTRO-OPTICAL CHARACTERISTICS ($T_a = 25^\circ\text{C}$)

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITIONS
Dark Current	I_R			30	nA	$V_R = 10\text{ V}$
Wave length of the max. sensitivity	λ_{MAX}		940		nm	
Quantum yield (Electron per photon)	η		0.88			$\lambda = 940\text{ nm}$
Spectral sensitivity	S	35	50		nA/lx	$V_R = 5\text{ V}$
Spectral sensitivity	S		0.6		A/W	$\lambda = 940\text{ nm}$
Open circuit voltage	V_L		285		mV	$E_V = 100\text{ lx}$
Open circuit voltage	V_L		365		mV	$E_V = 1\ 000\text{ lx}$
Rise and fall time of the photocurrent from 10 % to 90 % and 90 % to 10 % of the final value	t_r, t_f		125		ns	$R_L = 1\text{ k}\Omega, V_R = 0\text{ V}, \lambda = 940\text{ nm}$
	t_r, t_f		50		ns	$R_L = 1\text{ k}\Omega, V_R = 5\text{ V}, \lambda = 940\text{ nm}$
Capacitance	C_t		14		pF	$V_R = 5\text{ V}, f = 1\text{ MHz}$
Radiant sensitive area	A		9		mm ²	
Noise equivalent power	NEP		4.2×10^{-14}		$\text{W}/\sqrt{\text{Hz}}$	$V_R = 10\text{ V}$
Detection limit	D		6.6×10^{13}		$\text{cm}\sqrt{\text{Hz/W}}$	

TYPICAL CHARACTERISTICS ($T_a = 25^\circ\text{C}$)



LEAK CURRENT vs. SUPPLY VOLTAGE



LEAK CURRENT vs. AMBIENT TEMPERATURE

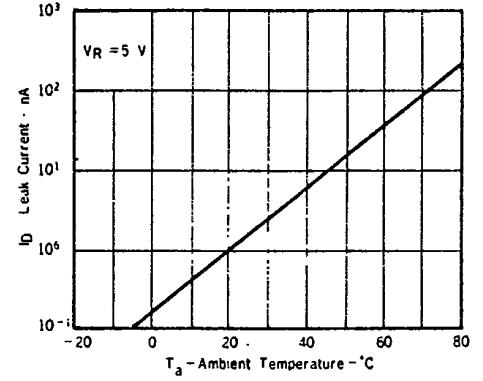
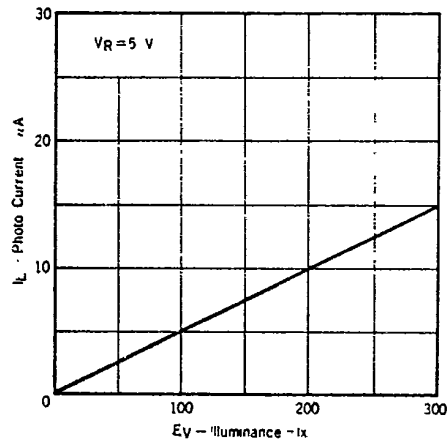


PHOTO CURRENT vs. ILLUMINANCE



RELATIVE vs. AMBIENT TEMPERATURE

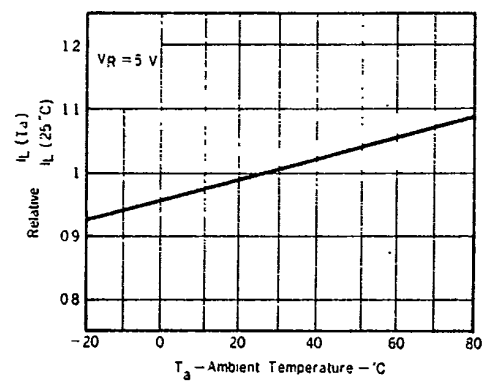


PHOTO CURRENT vs. SUPPLY VOLTAGE

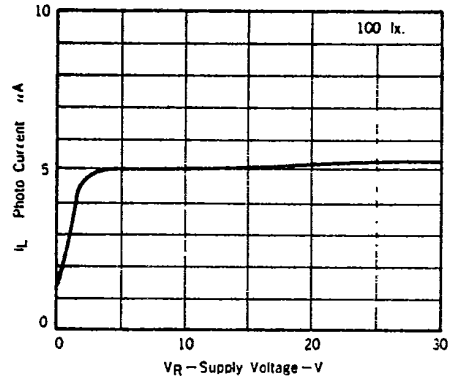
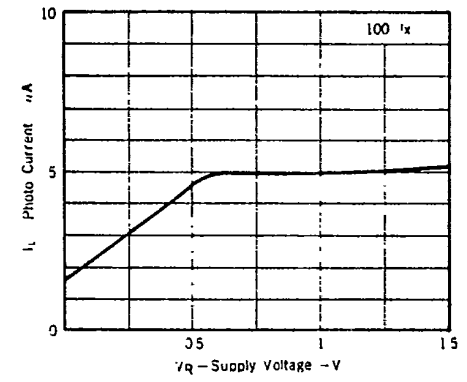
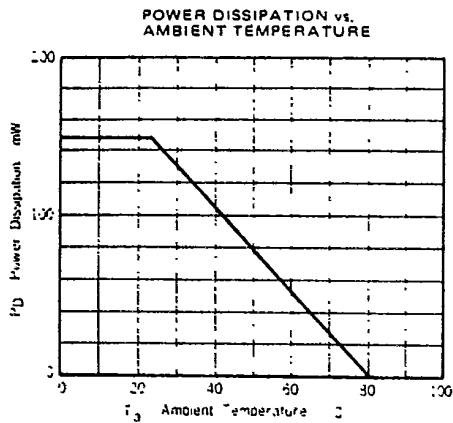


PHOTO CURRENT vs. SUPPLY VOLTAGE



PH302

T-41-53

**HANDLING PRECAUTIONS:**

1. The full resin-molded PH302 has generally a little less mechanical and thermal strength than other resin-molded semiconductor devices as they have less additives. Therefore please note on the following points.
 - (a) Soldering of leads should be made at the point 5 mm or more from the root of the leads at 260 °C and within 5 s.
 - (b) If the temperature of the molded portion rises in addition to the residual stress between the leads, the possibility that open or short circuit occurs due to the deformation or destruction of the resin will increase.
2. On cleaning the device:
 - (a) Cleaning with unsuitable solvent may impair the resin if the package and the following solvents should be used at the temperature of less than 45 °C and for less than 3 minutes of immersion time.
 - Ethanol, Methanol
 - Isopropyl-alcohol
 - (b) Ultrasonic cleaning will add some stress on devices. The degree of the stress differs depending on the oscillation output power, the size of the PCB and the mounting methods of the devices, therefore it should be confirmed by making an experiment at actual conditions that the cleaning does not have any problem on the devices.